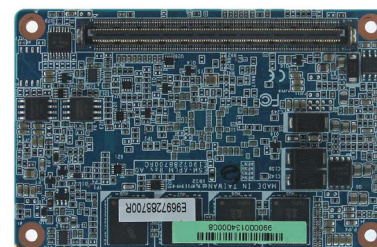
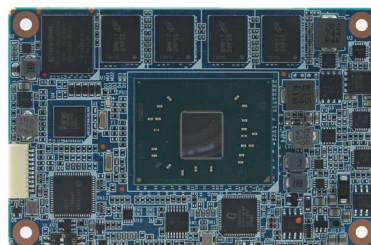


Features

- COM Express™ 3.0 Mini Type 10 module with Intel® Celeron® N3350 SoC BGA Processor
- Onboard 4GB DDR3L memory, optional 8GB
- Optional eMMC for storage
- Intel® Gen9 Low Power graphics, up to 4K resolution and H.265 codec
- 1 x PCIe x4 (Supports x1, x2, x4, optional 1 x PCIe x4 when Ethernet is removed) compliant to PCIe Gen2 5.0 GT/s
- 2 x SATA III 6 Gb/s, 2 x USB 3.1 (Gen1) and 8 x USB 2.0



Specifications

System	
CPU	Intel® Celeron® N3350 2.40 GHz (Burst) 1.1 GHz Clock Dual Core L2 cache 1MB 6W TDP Please note: CPU coolers are not included. Please see Ordering Info tab for more details.
System Chipset	Integrated in SoC
System Memory	Onboard 4GB DDR3L Optional 8GB DDR3L
SSD	Optional eMMC 5.1 up to 128GB
Audio	Intel® HD Audio integrated in SoC
Ethernet	Intel® Ethernet Controller I211-AT 10/100/1000 GbE Connection
BIOS	AMI UEFI BIOS, 128Mbit SPI Flash ROMM
I/O Chip	IT8528
Expansion	1 PCIe x4 (Supports x1, x2, x4, optional 1 PCIe x4 while removing Ethernet) compliant to PCIe Gen2 5.0 GT/s
OS Support	Microsoft® Windows 10 Linux (Kernel 4.6 above)

Display	
Chipset	Intel® Atom™ SoC Integrated
LVDS	Single channel 18/24-bit LVDS from eDP-to-LVDS IC CH7511B LVDS: up to 1920 x 1080 @ 60 Hz
Digital Display Interface	DDIO supports DisplayPort/HDMI/DVI-D DisplayPort 1.2 up to 4096x2160@60Hz HDMI 1.4b: up to 3840 x 2160 @ 30 Hz
eDP	Optional eDP 1.3: up to 3840 x 2160 @ 60Hz

External I/O	
USB	2 x USB 3.1 (Gen1) and 8 x USB 2.0
SATA	2 x SATA III (6 Gb/s)
MIO	1 x SMBus, 1 x LPC
GPIO	1 x 8-bit GPIO

Mechanical & Environment	
Power Requirement	Standard Input ATX: 4.75V~20V, 5Vsb ±5%; AT: 4.75V~20V
Power Type	ATX/AT
Operating Temp	Standard: 0°C to 60°C (32°F ~ 140°F)
Storage Temp	-40°C ~ 75°C (-40°F ~ 167°F)
Operating Humidity	40°C @ 95% Relative Humidity, Non-condensing
Form Factor	COM Express Modules
Dimensions	84 x 55 mm (3.31" x 2.17")
Certification Info	CE, FCC Class B

Ordering Info	
ESM-APLM-N3350-B2R	Intel® Celeron® N3350 SoC Processor Type10 COMe Mini Module, Onboard 4GB DDR3L
EEV-EX15-B1R	Mini-ITX Carrier Board for COMe Type 10 A1
ACC-ESMAPLM-SK-1R	Heatsink for ESM-APLM without Fan H=26 mm
ACC-ESMAPLM-SK-2R	Heatsink for ESM-APLM without Fan H=26 mm with pad for eMMC
ACC-ESMAPLM-SD-1R	Heatspreader for ESM-APLM without Fan H=13 mm
ACC-ESMAPLM-SD-2R	Heatspreader for ESM-APLM without Fan H=13 mm with pad for eMMC

* All product specifications and images are subject to change without notice. Last update: 09/28/2023

